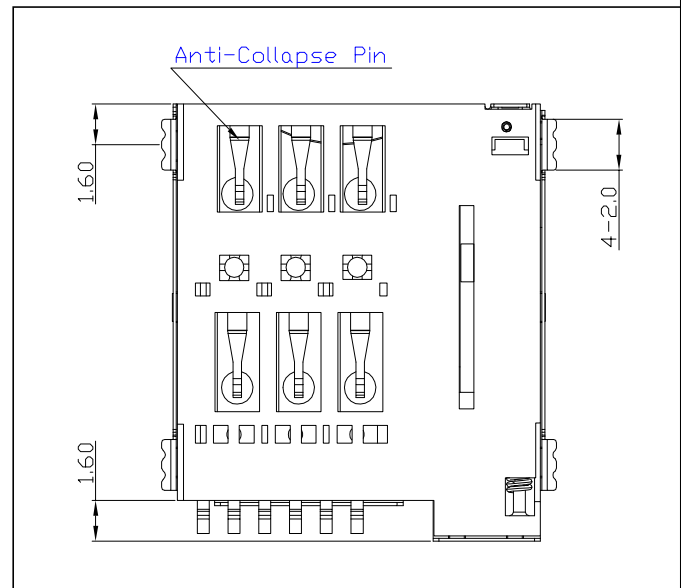
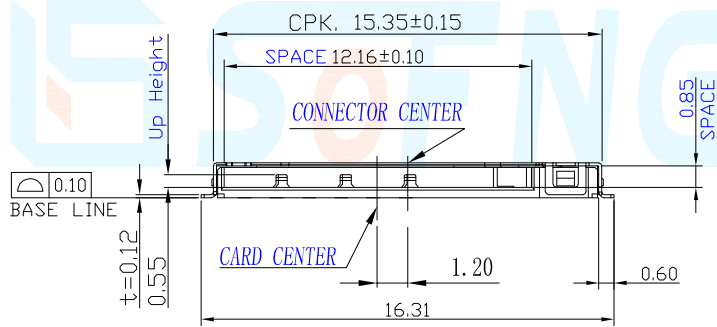
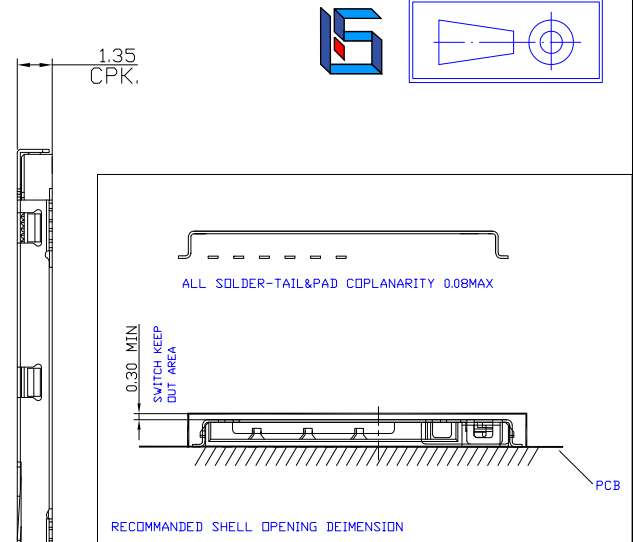
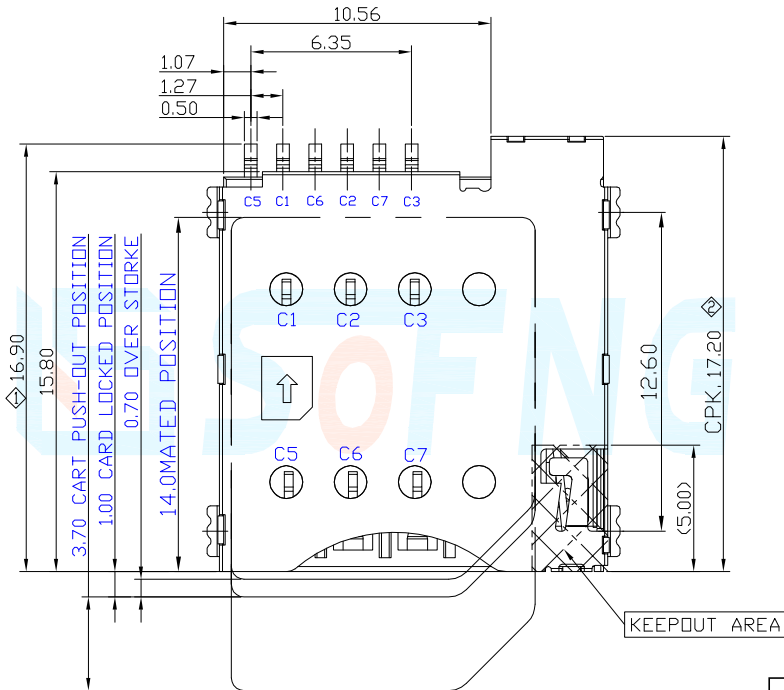


LTEM NO.: SIM-002-A6
(17.2×15.3×1.35 SIM CARD SOCKETS)

Unit:mm

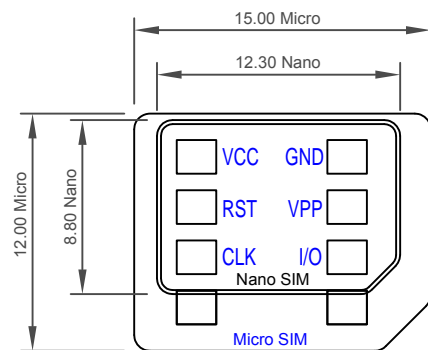


未标注尺寸依照 3D 文档; 未标注公差参考图

面公差表:

带▲标注为重点管制尺寸。

SIM CARD Pin DESIGN			
Pin No.	Pin NAME	Type	Description
C①	卡电源	□	VCC
C②	复位	□	RST
C③	时钟	□	CLK
C⑤	接地	□	GND
C⑥	Vpp	□	VPP
C⑦	输入/输出	□	I/O

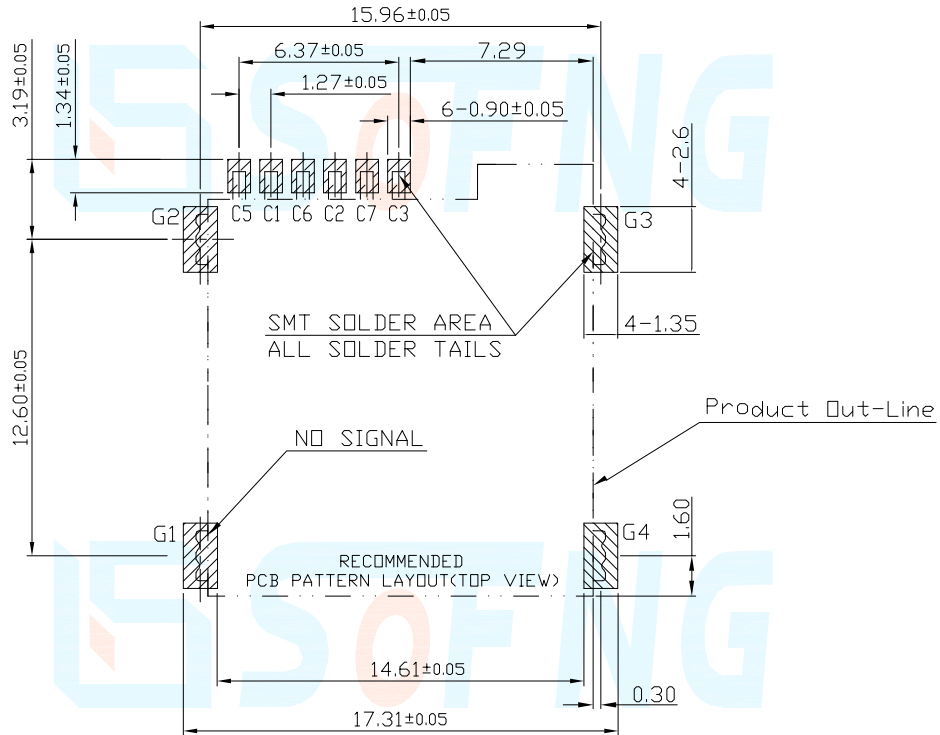


Reference

MICRO-SIM

CIRCUIT BOARD SIZE (Vertical view)

Operating Force	Inward	8.0~12.0N. (1N.=100gram-force)	Solder-ability (Max.)	
	Exiting	10.0N. (1N.=100gram-force)	IR Reflow:255°C, 5sec.	Manual:350°C, 3sec.



DECIMALS		ANGLES	
.X	:±0.25	X.°	:±1.5°
.XX	:±0.15	X.X°	:±1.0°
.XXX	:±0.10	.XXX°	:±0.5°



Technical parameter

PROJECT		LEVEL	A[better product]	B[average product]	C[low product]
Electrical Properties	Initial Contact Resistance		30mΩ max.	30mΩ max.	no data!
	Contact Resistance		100MΩ min.100V DC Skey/PD: 50MΩ min.100V DC		
	Withstand Voltage		300V AC for 1min	250 V AC for 1min	
Durable Performance	There No Load		8,000 Cycles	7,000 Cycles	no data!
	Rated Load		6,500 Cycles 50mΩ max.	5,000 Cycles 30mΩ max.	no data!
Insertion Force			4.0Kgf MAX (Springback:)		

表面貼裝 SMT

側向導入 LATERAL

精密部品 NICETY

可靠 STABILIZE

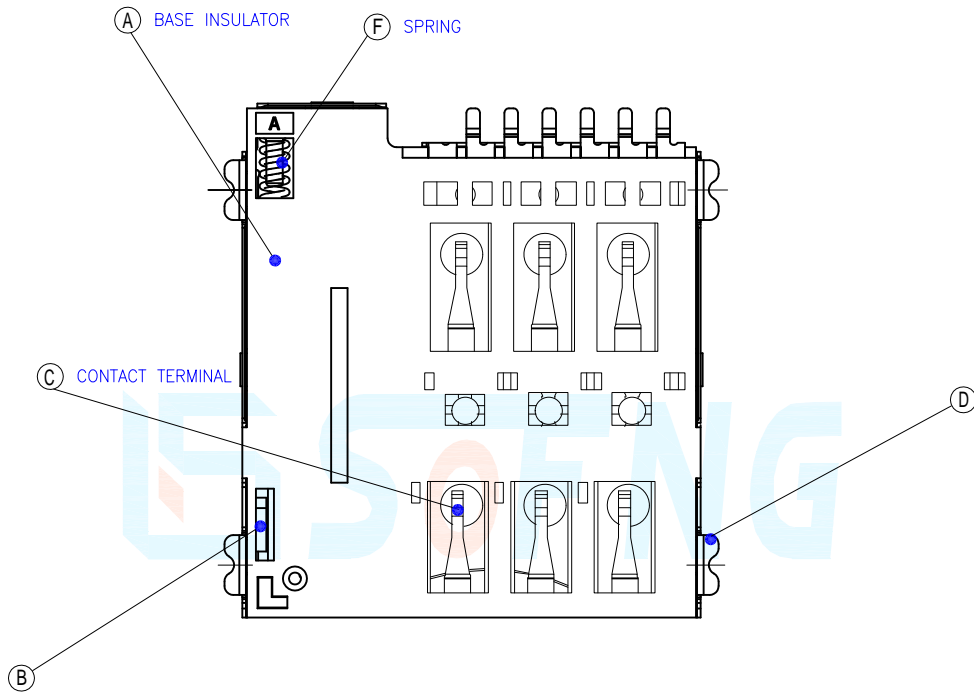
適合環保 RoHS

Material declaration			
No.	NAME	MATERIAL	PLATING
① A	基座	LCP 30%G/F (Black)耐热塑胶	-
② B	滑块	PA6T 30%G/F (Black)耐热尼龙	SET
③ C	接触端子	C5191R-H (t=0.15mm)磷青铜【锡 30u" 基镀金 3u"】	G/F
④ D	外壳	SUS301 (t=0.12mm)【AU/Ni焊区镀金1u"】	G/F
⑤ E	线簧	象唛钢线 OD=0.21mm	-
⑥ F	弹簧	SUS304(t=0.30mm)不锈钢	-

本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。Products do not belong to hazardous waste, When waste can recycling processing

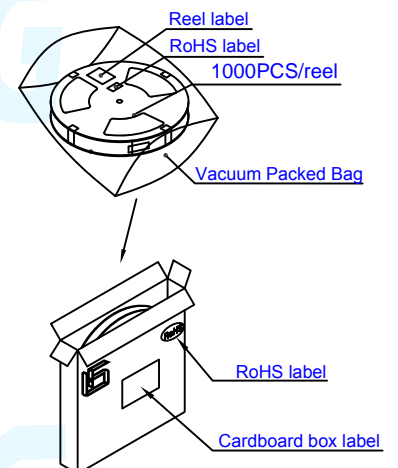
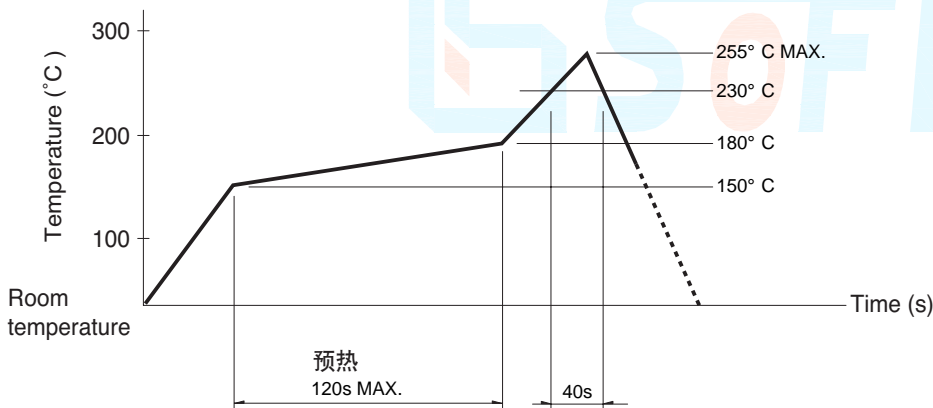
運送時本產品不要直接與水、酸鹼性化學物質接觸,或放置於含有以上氣體環境中,並且需要注意會有以上氣體環境中,並且需要注意會有滑落、側翻的危險發生;運輸過程中不能有碰撞或者擠壓,須保證溫度與濕度適中[常溫 25℃,濕度在 50℃以內],不可導致材料變形或氧化。

Other size



回流方式的參考舉例

1. 加熱方式遠紅外線加熱的上下加熱方式。
2. 溫度測量方式用 V0.1 ~ V0.2 的 CA(K) 或 CC(T) 進行測量。
3. 溫度分布



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